	connecto	ors							
SPECIFICATION									
宏致	電子股份有	限公司							
	桃園縣中壢市東園路13號								
	No.13, Dongyuan Rd., Jhongli	City,							
	Taoyuan County 320, Taiwan (R	.O.C.)							
	TEL: +886-3-463-2808 FAX: +886-3-463-1800								
SPEC. NO.: <u>PS-9200</u>	4-XXXXX RI	EVISION: <u>A</u>							
PRODUCT NAME: 2.54MM MICRO POWER QUADLOK									
PRODUCT NO:	92004-0401L-001								
PREPARED:	CHECKED:	APPROVED:							
LLJ	ANDREW	SIMON							
DATE: 2014/08/12	DATE: 2014/08/12	DATE: 2014/08/12							

	ectors		Aces P/N: 92004-XXXXX serie	S
TITLE:	2.54MM MIC	RO POWER QUAI	DLOK	
RELEASE D	ATE: 2014/08/12	REVISION: A	ECN No:1406001	PAGE: 2 OF 7
1 2 3 4 5 6	REVISION HI SCOPE APPLICABLE REQUIREME PERFORMAN	STORY E DOCUMENTS NTS ICE	ECN No: 1406001	

# 

# Aces P/N: 92004-XXXXX series

#### TITLE: 2.54MM MICRO POWER QUADLOK

RELEASE DATE: 2014/08/12 REVISION: A

ECN No:1406001

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## **1** Revision History

Rev.	ECN #	Revision Description	Prepared	Date
0	ECN-1112223	NEW RELEASED	STANLEY	2011.12.13
Α	ECN-1406001	Terminal / Housing Retention Force Is 2.5kgfMin	LLJ	2014.08.12

	<b>Connectors</b>			Aces P/N:	2004-XXXX	series	
Т	TTLE: 2.54N	AM MICRC	POWER QUA	ADLOK			
REL	EASE DATE: 20	14/08/12	REVISION: A		ECN No:1406001		PAGE: <b>4</b> OF <b>7</b>
2	SCOPE	ecification	covers perfor	mance tests	s and quality rec	uirements for	2 54mm Micro
3	Power	Quadlok Th	CUMENTS				
			ICS INDUSTR	IES ASSOCI	ATION		
4	REQUIRE	EMENTS					
	4.1 Design	and Constru	uction				
	4.1.1			, construction a	and physical dimen	sions specified o	n applicable
	4.1.2	product dra All materia		o.H.S. and the	standard depends	on TQ-WI-1401	01.
	4.2 Materia	ls and Finis	h				
	<ul> <li>4.2.1 Contact: High performance copper alloy</li> <li>Finish: (a) Contact Area: Tin plated</li> <li>(b) Under plate: Nickel-plated all over</li> <li>(c) Solder area: Tin plated</li> </ul>						
	4.2.2	Housing: T	hermoplastic H	High Temp., l	JL94V-0		
	4.3 Ratings	i					
	4.3.2	Current: 3	) Volts AC (pe Amperes (per Femperature : -	pin)	°C		
<u> </u>				Page	4	2010/10/31	TR-FM-73015L

ACES

### Aces P/N: 92004-XXXXX series

# TITLE: 2.54MM MICRO POWER QUADLOK

RELEASE DATE: 2014/08/12 REVISION: A

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#### Performance

5.1. Test Requirements and Procedures Summary

ltem	Requirement	Standard			
Examination of Product	Product shall meet requirements of applicable product drawing and specification.				
	ELECTRICAL				
Item	Standard				
Low Level Contact Resistance	20 m Ω Max.(initial)per contact $\triangle R$ (after test)15 m Ω Max.	Mate connectors, measure by dry circuit, 20mV Max., 100mA Max. (EIA-364-23)			
Insulation Resistance	100 M Ω Min.	Unmated connectors, apply 500 V DC between adjacent terminals. (EIA-364-21)			
Dielectric Withstanding Voltage	No discharge, flashover or breakdown. Current leakage: 1 mA max.	300 VAC Min. at sea level for 1 minute. Test between adjacent contacts of unmated connectors. (EIA-364-20)			
Temperature rise	30°C Max. Change allowed	Mate connector: measure the temperature rise at rated current until temperature stable. The ambient condition is still air at 25°C (EIA-364-70METHOD1,CONDITION 1)			
	MECHANICAL				
Item	Requirement	Standard			
Mating / Unmating Forces	Mating Force: 20 Kg Max. (With Lock) Unmating Force: 25 Kg Max. (Without Lock)	Operation Speed : 25.4±3mm/minute. Measure the force required to mate/Unmate connector. (EIA-364-13)			
Vibration	1 μs Max.	The electrical load condition shall be 100 mA maximum for all contacts. Subject to a simple harmonic motion having amplitude of 0.76mm (1.52mm maximum total excursion) in frequency between the limits of 10 and 55 Hz. The entire frequency range, from 10 to 55 Hz and return to 10 Hz, shall be traversed in approximately 1 minute. This motion shall be applied for 2 hours in each of three mutually perpendicular directions.			

ACES

#### Aces P/N: 92004-XXXXX series

#### TITLE: 2.54MM MICRO POWER QUADLOK

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		(EIA-364-28 Condition I)		
Terminal / Housing Retention Force	2.5kgf Min.	Apply axial pull out force at the speed rate of 25.4 ± 3 mm/minute. On the terminal assembled in the housing.		
Shock (Mechanical)	1 µs Max.	Subject mated connectors to 50 G's (peak value) half-sine shock pulses of 11 milliseconds duration. Three shocks in each direction shall be applied along the three mutually perpendicular axes of the test specimen (18 shocks). The electrical load condition shall be 100mA maximum for all contacts. (EIA-364-27, test condition A)		
	ENVIRONMENTA			
ltem	Requirement	Standard		
Resistance to <b>Wave</b> Soldering Heat	See Product Qualification and Test Sequence Group 6 (Lead Free)	Solder Temp. ∶ 265±5℃, 10±0.5sec.		
Thermal Shock	See Product Qualification and Test Sequence Group <mark>4</mark>	Mate module and subject to follow condition for 5 cycles. 1 cycles: -55 +0/-3 °C, 30 minutes +85 +3/-0 °C, 30 minutes (EIA-364-32, test condition I)		
Humidity	See Product Qualification and Test Sequence Group 4	Mated Connector 40°C, 90~95% RH, 96 hours. (EIA-364-31,Condition A, Method II)		
Solder ability	Solder able area shall have minimum of 95% solder coverage.	And then into solder bath, Temperature at 245 ±5°C, for 4-5 sec. (EIA-364-52)		
Low Temperature test	See Product Qualification and Test Sequence Group 7	hours. Measure Signal. (EIA-364-59)		
Temperature life(Heat)	See Product Qualification and Test Sequence Group <mark>8</mark>	Subject mated connectors to		

# Aces P/N: 92004-XXXXX series

#### TITLE: 2.54MM MICRO POWER QUADLOK

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# 5 PRODUCT QUALIFICATION AND TEST SEQUENCE

**REVISION:** A

	Test Group							
Test or Examination	1	2	3	4	5	6	7	8
	Test Sequence							
Examination of Product				1、7		1	1、6	1、6
Low Level Contact Resistance		1	1、4	2、10		3	2 \ 9	2 • 9
Insulation Resistance				3 \ 9			3 \ 8	3 \ 8
Dielectric Withstanding Voltage				4 • 8			4 \ 7	4 \ 7
Temperature rise	1							
Mating / Unmating Forces		2						
Terminal / Housing Retention Force					1			
Vibration			2					
Shock (Mechanical)			3					
Thermal Shock				5				
Humidity				6				
Solder ability					2			
Resistance to Wave Soldering Heat						2		
Low Temperature test							5	
Temperature life (Heat)								5
Sample Size	2	4	4	4	2	4	4	4